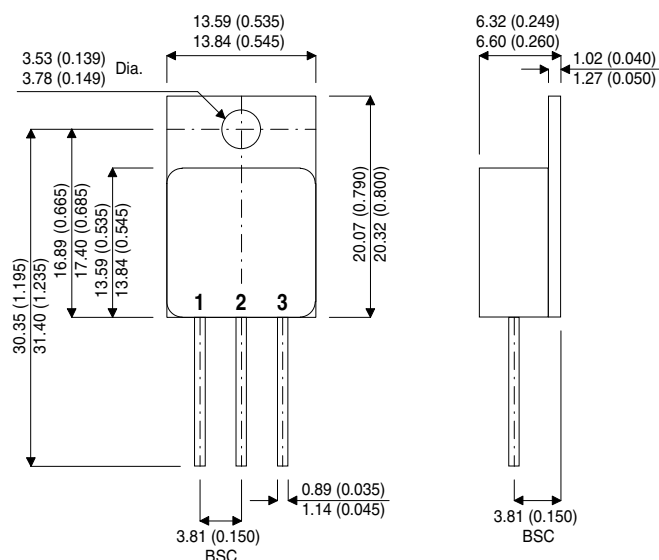


MECHANICAL DATA

Dimensions in mm (inches)



TO254 PACKAGE

Pin 1 – Drain

Pin 2 – Source

Pin 3 – Gate

N-CHANNEL POWER MOSFET FOR HI-REL APPLICATIONS

V_{DSS} 100V

I_{D(cont)} 18A

 $R_{DS(on)} \quad 0.092\Omega$

FEATURES

- **HERMETICALLY SEALED TO254 METAL PACKAGE**
- **SIMPLE DRIVE REQUIREMENTS**
- **LIGHTWEIGHT**
- **SCREENING OPTIONS AVAILABLE**
- **ALL LEADS ISOLATED FROM CASE**

ABSOLUTE MAXIMUM RATINGS ($T_{case} = 25^{\circ}C$ unless otherwise stated)

V_{GS}	Gate – Source Voltage	$\pm 20V$
I_D	Continuous Drain Current @ $T_{case} = 25^{\circ}C$	18A
I_D	Continuous Drain Current @ $T_{case} = 100^{\circ}C$	12A
I_{DM}	Pulsed Drain Current	72A
P_D	Power Dissipation @ $T_{case} = 25^{\circ}C$	50W
	Linear Derating Factor	TBA
T_J, T_{stg}	Operating and Storage Temperature Range	-55 to $150^{\circ}C$
$R_{\theta JC}$	Thermal Resistance Junction to Case	TBA $^{\circ}C/W$ max.
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	TBA $^{\circ}C/W$ max.

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ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise stated)

Parameter		Test Conditions		Min.	Typ.	Max.	Unit
STATIC ELECTRICAL RATINGS							
BV _{DSS}	Drain – Source Breakdown Voltage	V _{GS} = 0	I _D = 1mA	100			V
ΔBV _{DSS}	Temperature Coefficient of Breakdown Voltage	Reference to 25°C I _D = 1mA			0.1		V/°C
R _{DS(on)}	Static Drain – Source On–State Resistance	V _{GS} = 10V	I _D = 12A			0.092	Ω
		V _{GS} = 10V	I _D = 18A			0.11	
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS}	I _D = 250μA	2		4	V
g _{fs}	Forward Transconductance	V _{DS} ≥ 15V	I _{DS} = 12A	9.1			S(ṽ)
I _{DSS}	Zero Gate Voltage Drain Current	V _{GS} = 0	V _{DS} = 0.8BV _{DSS}			25	μA
			T _J = 125°C			250	
I _{GSS}	Forward Gate – Source Leakage	V _{GS} = 20V				100	nA
I _{GSS}	Reverse Gate – Source Leakage	V _{GS} = –20V				-100	
DYNAMIC CHARACTERISTICS							
C _{iss}	Input Capacitance	V _{GS} = 0			1660		pF
C _{oss}	Output Capacitance	V _{DS} = 25V			550		
C _{rss}	Reverse Transfer Capacitance	f = 1MHz			120		
Q _g	Total Gate Charge	V _{GS} = 10V	I _D = 18A	30		59	nC
		V _{DS} = 0.5BV _{DSS}					
Q _{gs}	Gate – Source Charge	I _D = 18A		2.4		12	nC
Q _{gd}	Gate – Drain (“Miller”) Charge	V _{DS} = 0.5BV _{DSS}		12		30.7	
t _{d(on)}	Turn–On Delay Time	V _{DD} = 50V I _D = 18A R _G = 9.1Ω				21	ns
t _r	Rise Time					145	
t _{d(off)}	Turn–Off Delay Time					64	
t _f	Fall Time					105	
SOURCE – DRAIN DIODE CHARACTERISTICS							
I _S	Continuous Source Current					18	A
I _{SM}	Pulse Source Current					73	
V _{SD}	Diode Forward Voltage	I _S = 18A	T _J = 25°C			1.5	V
		V _{GS} = 0					
t _{rr}	Reverse Recovery Time	I _S = 18A	T _J = 25°C			400	ns
Q _{rr}	Reverse Recovery Charge	d _i / d _t ≤ 100A/μs V _{DD} ≤ 50V				2.4	μC
PACKAGE CHARACTERISTICS							
L _D	Internal Drain Inductance	(from 6mm down drain lead pad to centre of die)			TBA		nH
L _S	Internal Source Inductance	(from 6mm down source lead to centre of source bond pad)			TBA		

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